



PATENT
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IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Noriaki ODA

Conf. 2345

Application No. 10/761,204

Group 2826

Filed January 22, 2004

Examiner A. Williams

SEMICONDUCTOR DEVICE WITH BONDING
PAD SUPPORT STRUCTURE

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

March 14, 2006

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying documents, copies of which are attached to this statement, are made of record on the enclosed Form PTO-1449.

A concise explanation of the relevance of these items is that these references were cited by the German Patent Office in an Official Action. JP 2001-015516 and JP 2001-267323 were previously cited in the Information Disclosure Statement filed January 22, 2004.

Please charge the fee of \$180 required by 37 CFR 1.17(p) to Deposit Account No. 25-0120.

Respectfully submitted,

YOUNG & THOMPSON

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Group Art Unit:
2826

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* Abstract provided for the Examiner's convenience